

Micro G Switch **Bottom Contact** Model AT-500-B

FEATURES:

- Small and Lightweight 3.4 mm²

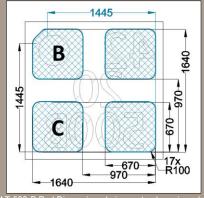
- Surface Mount Au over Ni Pads
- Tape and Reel Packaging
- Environmental Seal

APPLICATIONS:

- Arming / Fuzing
- More







AT-500-B Pad Dimensions (micrometers) as viewed from PAD side of device

Specifications

OPERATING CHARACTERISTICS:

Sensitivity (5)	+Z (normal to PCB)	
Contact Acceleration Thresholds (nominal)	350 to 650	g
Contact Type (3)	Normally Open, Non-Latching	•
Response Time (2)	< 175	μS
Reset Autor		•

ELECTRICAL CHARACTERISTICS

Contact Resistance (1)<10	ohms
Insulation Resistance (min.)	
Breakdown Voltage>200	

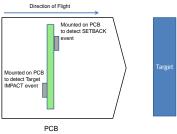
ENVIRONMENTAL RATINGS:

Operate Temperature Range55 to +125	$^{\circ}\text{C}$
Storage Temperature Range55 to +125	°C
PCB/Pad Shear Force>20	N
Shock Survival (4)>65000	g

PHYSICAL CHARACTERISTICS:

Nominal Dimensions (LxWxH)1	.84 x 1.84 x 1.3	mm
Volume		
Mass		
ROHS Compliant?	Yes	9

- (1) Contact resistance is dependent on input pulse acceleration level.
- (2) Response time depends upon input pulse profile.
- (3) Electrical connections between pads 'C'(common) and and 'B' (bottom) are normally open and will close while acceleration is greater than the contact acceleration threshold.
- The Micro G Switch devices are designed to survive the extreme high shock environments associated with artillery launch events.
- The diagram below provides guidance on how to mount the switch for setback or impact detection.



Note that the information on this data sheet is for reference only.

As each application may have unique requirements, please verify the specifications as well as suitability of using our products in your applications by consulting our engineering department.

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